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Orderable: Shipable	Designed for: Public Release	Mod. Date: 11/15/2017
TID #: TIDA-01498	Project Title: SEPIC Coupled Inductor	
Number: TIDA-01498	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By:	File: SEPIC_Coupled.SchDoc	Size: B
Engineer: Ingolf Frank	Contact: http://www.ti.com/support	



H1 SJ-5303 (CLEAR) H4 SJ-5303 (CLEAR) H7 SJ-5303 (CLEAR) H10 SJ-5303 (CLEAR)

DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-01498
PCB Rev: E1

PCB LOGO Pb-Free Symbol PCB LOGO FCC disclaimer


Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIDA-01498	Project Title: SEPIC Coupled Inductor		
Number: TIDA-01498	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2	
Drawn By: Ingolf Frank	File: EVM_Hardware-No-Logo.SchDoc	Size: B	
Engineer: Ingolf Frank	Contact: http://www.ti.com/support		

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